

### ❖ Features:

- Package: 1.0\*0.5\*0.45 mm
- Mono-color type
- Soldering methods :All SMT assembly methods
- Comply ROHS standard

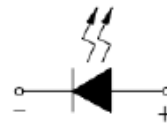
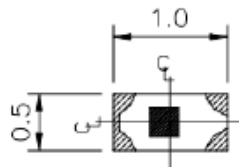
### ❖ Description

The Blue source color devices are made with InGaN on sapphire Light Emitting Diode.

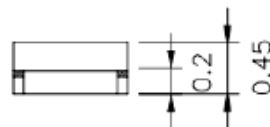
### ❖ Application

- LCD backlight
- Illuminations

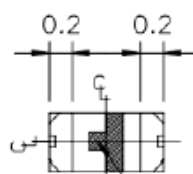
### ❖ Package Dimensions



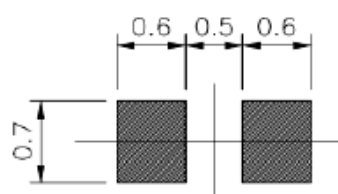
POLARITY



For Reflow Soldering



Cathode Mark



### NOTES:

1. All dimensions are in millimeter[unit];
2. Tolerance is  $\pm 0.1\text{mm}$  ( $0.004''$ ) unless other specified;
3. Specifications are subject to change without notice.

Emitted Color	Lens Color	Chip Material
Pure White	Yellow Diffused	InGaN

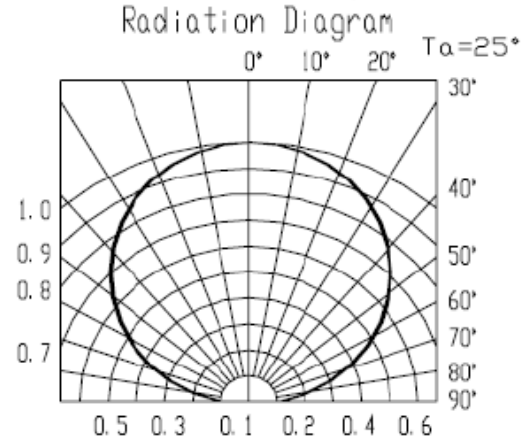
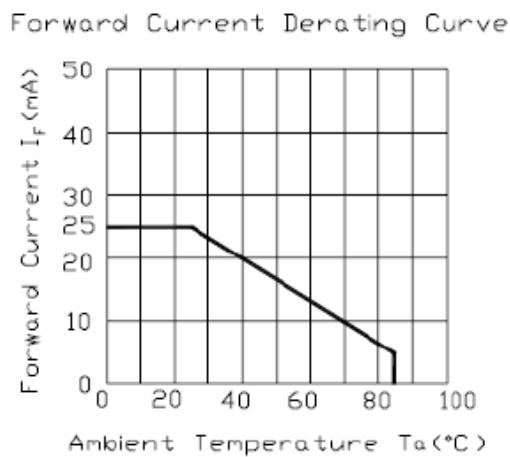
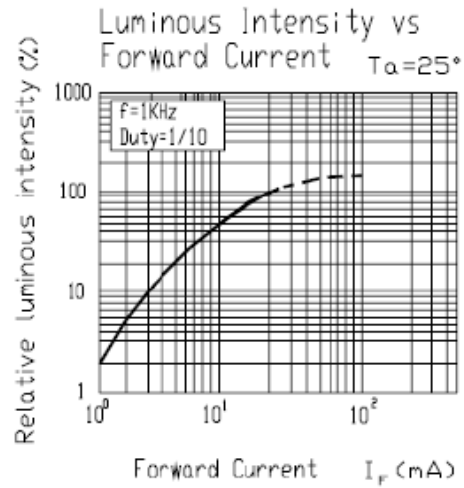
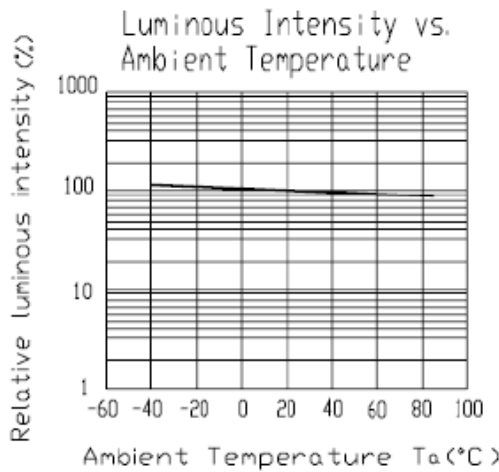
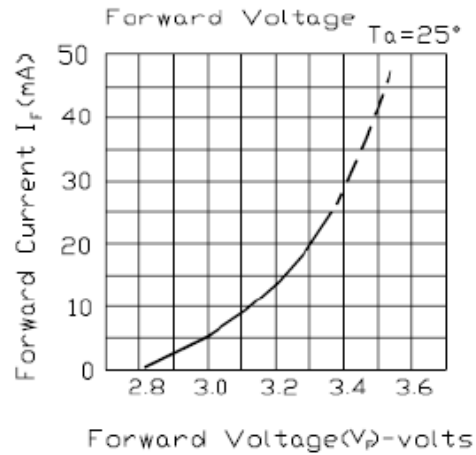
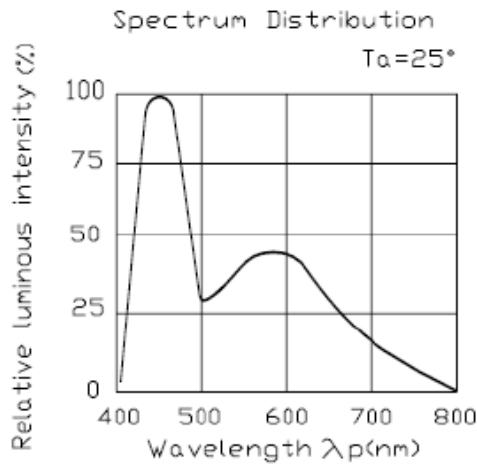
### ◇ Absolute Maximum Ratings(Ta=25°C)

Item	Symbol	Maximum	Unit
Power Dissipation	PD	110	mW
Continuous Forward Current	I <sub>Fmax</sub>	25	mA
Peak Forward Current(1/10 Duty Cycle 0.1ms Pulse Width)	I <sub>FP</sub>	100	mA
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature Range	T <sub>opr</sub>	-40 to+85	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to+85	°C
Lead Solder Temperature	T <sub>sol</sub>	260°C for 3 seconds	

### ◇ Electrical/Optical Characteristics(Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	2.7	--	3.6	V
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =20mA	45	--	120	mcd
CIE Coordinates	X	I <sub>F</sub> =20mA		0.31		--
	Y			0.31		
Typical Correlated Color Temperature	T <sub>c</sub>	I <sub>F</sub> =20mA	5000	7000	9000	K
Viewing Angle	2θ <sub>1/2</sub>	I <sub>F</sub> =20mA	--	120	--	Deg
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	--	--	10	uA

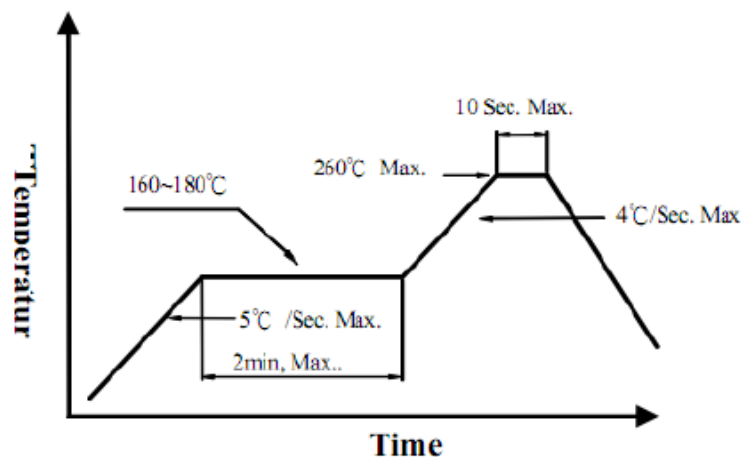
❖ Typical Electro-Optical Characteristics Curves



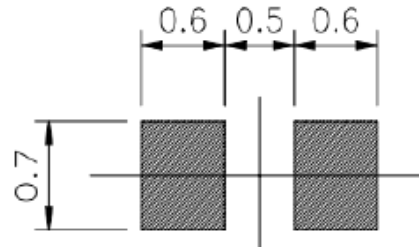
❖ Reliability Test Items And Conditions

NO.	Item	Test Condition	Test Hr/cycle/time	Sample Q'ty	Ac/Re
1	Reflow	TEMP:260±5°C; Min.5Sec	6 min	22pcs	0/1
2	Temperature Cycle	H:+90°C 30mins To(5mins) L:-30°C 30mins	300 cycles	22pcs	0/1
3	Thermal Shock	H:+100°C 20mins To(5mins) L:-40°C 20mins	100 cycles	22pcs	0/1
4	High Temperature Storage	TEMP:+100°C	1000hrs	22pcs	0/1
5	Low Temperature Storage	TEMP:-30°C	1000hrs	22pcs	0/1
6	DC Operating Life	IF=20MA	1000hrs	22pcs	0/1
7	High Temperature	65°C	240hrs	22pcs	0/1
8	High Humidity	R.H.= 85%		22pcs	0/1

❖ Reflow Temp/Time :



❖ Recommended Soldering Pad Dimensions:



❖ Tape Specification

